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(54) SEALING MATERIAL, MOLD FOR MANUFACTURING THE SEALING MATERIAL, AND COMPOSITE FOR SEAL AND MANUFACTURING METHOD THEREFOR

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a composite for a seal with a low hardness and easy-to-mold sealing material, having excellent dust resistance, waterproofness or the like and superior adhesiveness to a cover member not to cause detachment and allowing use as a high-performance gasket, satisfactory in durability and adhesiveness between the seal material and the cover member.

SOLUTION: This composite for the seal has the sealing material circumferentially extending on the cover member. In section of the seal material in a direction nearly orthogonal to the extension direction of the sealing material, a portion of $(L_m/L_p) \leq 3$ is 50% or higher to the full length of the seal material, wherein L_p is a length of a contact part with the cover member, and L_m is a length of a non contact part with the cover member. Preferably, the portion of $(L_m/L_p) \leq 3$ is present evenly to the full length of the seal material, or the sealing material has a taper face.

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